

Title (en)

METHOD FOR PRODUCING AT LEAST ONE HIGH-FREQUENCY CONTACT ELEMENT OR A HIGH-FREQUENCY CONTACT ELEMENT ASSEMBLY AND ASSOCIATED DEVICES

Title (de)

VERFAHREN ZUR HERSTELLUNG VON MINDESTENS EINEM HOCHFREQUENZ-KONTAKTELEMENT ODER EINER HOCHFREQUENZ-KONTAKTELEMENT-ANORDNUNG SOWIE ZUGEHÖRIGE VORRICHTUNGEN

Title (fr)

PROCÉDÉ DE FABRICATION D'AU MOINS UN ÉLÉMENT DE CONTACT HAUTE FRÉQUENCE OU D'UN ENSEMBLE D'ÉLÉMENT DE CONTACT HAUTE FRÉQUENCE AINSI QUE DES DISPOSITIFS ASSOCIÉS

Publication

**EP 3555967 A1 20191023 (DE)**

Application

**EP 19703289 A 20190204**

Priority

- DE 102018104264 A 20180226
- EP 2019052562 W 20190204

Abstract (en)

[origin: WO2019162066A1] The invention relates to a method for producing at least one high-frequency contact element (2) or a high-frequency contact element assembly made of at least one such high-frequency contact element (2). The method includes the production of a base part (1) of each high-frequency contact element (2) from a dielectric material by means of an additive fabrication method, wherein the base part (1) has a via (4) between a first end (61) and a second end (62) of a longitudinal extent (3) of the base part (1). In addition, the method includes the coating of the dielectric base part (1) with an electrically conductive layer (5) and the removal of the electrically conductive layer (5) in a region surrounding the via (1) at the first end (61) and at the second end (62) of the base part (1) to form an electrically conductive coating (51) on the external conductor side and an electrically conductive coating (52) on the inner conductor side. The invention further relates to a method for producing a high-frequency contact element (2) or a high-frequency contact element assembly.

IPC 8 full level

**H01R 13/03** (2006.01)

CPC (source: EP US)

**H01R 13/035** (2013.01 - EP); **H01R 13/2414** (2013.01 - US); **H01R 43/007** (2013.01 - US); **H01R 43/16** (2013.01 - EP US); **H01R 12/7076** (2013.01 - EP); **H01R 12/714** (2013.01 - EP US); **H01R 12/73** (2013.01 - EP); **H01R 13/035** (2013.01 - US); **H01R 13/2414** (2013.01 - EP); **H01R 13/2421** (2013.01 - EP); **H01R 13/2442** (2013.01 - EP); **H01R 13/2485** (2013.01 - EP); **H01R 13/2492** (2013.01 - EP); **H01R 13/6476** (2013.01 - EP); **H01R 24/50** (2013.01 - EP US); **H01R 43/007** (2013.01 - EP); **H01R 2201/20** (2013.01 - EP US); **Y10T 29/49204** (2015.01 - US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2019162066 A1 20190829**; CN 112136250 A 20201225; CN 112136250 B 20220408; DE 102018104264 A1 20190829; EP 3555967 A1 20191023; EP 3555967 B1 20201216; US 11984693 B2 20240514; US 2020403364 A1 20201224

DOCDB simple family (application)

**EP 2019052562 W 20190204**; CN 201980015655 A 20190204; DE 102018104264 A 20180226; EP 19703289 A 20190204; US 201916975854 A 20190204